

SDM9435AQ

-30V P-Channel MOSFETs

Rev A.0

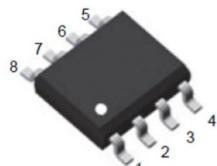
Feature

- ✧ Excellent $R_{DS(ON)}$
- ✧ Low Gate Charge
- ✧ Advanced Trench Technology
- ✧ Green product (RoHS compliant), lead free
- ✧ 100% UIS Tested

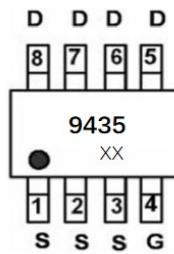
Product Summary

| | | |
|--|------|-----------|
| V_{DS} | -30 | V |
| $V_{GS(th)}_{Typ}$ | -1.8 | V |
| $R_{DS(ON)}_{Typ}$ (at $V_{GS} = -10V$) | 31 | $m\Omega$ |
| I_D (at $V_{GS} = -10V$) | -5.1 | A |

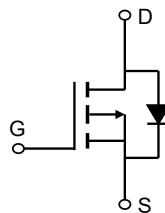
| Type | Package | Marking | Outline | Media | Quantity (pcs) |
|-----------|---------|---------|---------|----------|----------------|
| SDM9435AQ | SOP-8 | 9435 | Tape | 13" Reel | 4000 |



SOP-8 Top View



Marking and Pin Assignment



Schematic Diagram

Absolute Maximum Ratings (Rating at $T_A=25^\circ C$ unless otherwise noted)

| Parameter | | Symbol | Maximum | Unit |
|--|-------------------|----------------|-------------|------|
| Drain-Source Voltage | | V_{DS} | -30 | V |
| Gate-Source Voltage | | V_{GS} | ± 20 | V |
| Continuous Drain Current | $T_A=25^\circ C$ | I_D | -5.1 | A |
| | $T_A=100^\circ C$ | | -3.2 | |
| Pulsed Drain Current ⁽¹⁾ | | I_{DM} | -20 | A |
| Maximum Body-Diode Continuous Current | | I_S | -5.1 | A |
| Avalanche Energy ⁽²⁾ | | E_{AS} | 12 | mJ |
| Power Dissipation | $T_A=25^\circ C$ | P_D | 1.4 | W |
| Junction and Storage Temperature Range | | T_J, T_{STG} | -55 to +150 | °C |

SDM9435AQ



Electrical Characteristics (Rating at $T_J=25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------------|--|--|------|------|----------|------------------|
| STATIC PARAMETERS | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $I_D=-250\mu\text{A}, V_{GS}=0\text{V}$ | -30 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=-30\text{V}, V_{GS}=0\text{V}$ | - | - | -1 | μA |
| I_{GSS} | Gate-Body Leakage Current | $V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$ | - | - | ±100 | nA |
| $V_{GS(\text{th})}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=-250\mu\text{A}$ | -1.0 | -1.8 | -2.5 | V |
| $R_{DS(\text{ON})}$ | Static Drain-Source On-Resistance ⁽³⁾ | $V_{GS}=-10\text{V}, I_D=-5\text{A}$ | - | 31 | 40 | $\text{m}\Omega$ |
| | | $V_{GS}=-4.5\text{V}, I_D=-4\text{A}$ | - | 46 | 60 | |
| V_{SD} | Diode Forward Voltage | $I_S=-5.1\text{A}, V_{GS}=0\text{V}$ | - | - | -1.2 | V |
| DYNAMIC PARAMETERS | | | | | | |
| C_{iss} | Input Capacitance | $V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$ | - | 537 | - | pF |
| C_{oss} | Output Capacitance | | - | 73 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 55 | - | pF |
| SWITCHING PARAMETERS | | | | | | |
| Q_g | Total Gate Charge | $V_{GS}=-10\text{V}, V_{DD}=-15\text{V}, I_D=-2\text{A}$ | - | 10.9 | - | nC |
| Q_{gs} | Gate Source Charge | | - | 2.1 | - | nC |
| Q_{gd} | Gate Drain Charge | | - | 2.1 | - | nC |
| $t_{D(on)}$ | Turn-On Delay Time | $V_{GS}=-10\text{V}, V_{DD}=-15\text{V}, I_D=-2\text{A}, R_{\text{GEN}}=3\Omega$ | - | 2.9 | - | ns |
| t_r | Turn-On Rise Time | | - | 2.1 | - | ns |
| $t_{D(off)}$ | Turn-Off Delay Time | | - | 25 | - | ns |
| t_f | Turn-Off Fall Time | | - | 13 | - | ns |
| t_{rr} | Body Diode Reverse Recovery Time | $I_F=-2\text{A}, di/dt=100\text{A}/\mu\text{s}$ | - | 8.7 | - | ns |
| Q_{rr} | Body Diode Reverse Recovery Charge | $I_F=-2\text{A}, di/dt=100\text{A}/\mu\text{s}$ | - | 2.9 | - | nC |

Thermal Resistances

| Symbol | Parameter | Typ | Max | Unit |
|-----------------|--|-----|-----|---------------------------|
| $R_{\theta JA}$ | Thermal resistance from junction to ambient ⁽⁴⁾ | - | 89 | $^\circ\text{C}/\text{W}$ |

Notes:

- Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- EAS condition: Starting $T_J=25^\circ\text{C}$, $V_{DD}=-15\text{V}$, $V_G=-10\text{V}$, $R_G=25\text{ohm}$, $L=0.5\text{mH}$, $I_{AS}=-7\text{A}$
- Pulse Test: Pulse Width $\leq 300\text{us}$, Duty Cycle $\leq 0.5\%$
- $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB.

Typical Electrical and Thermal Characteristics

Figure 1: Saturation Characteristics

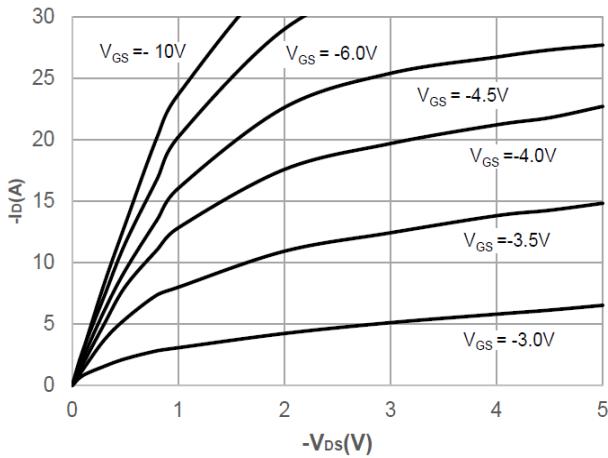


Figure 2: Transfer Characteristics

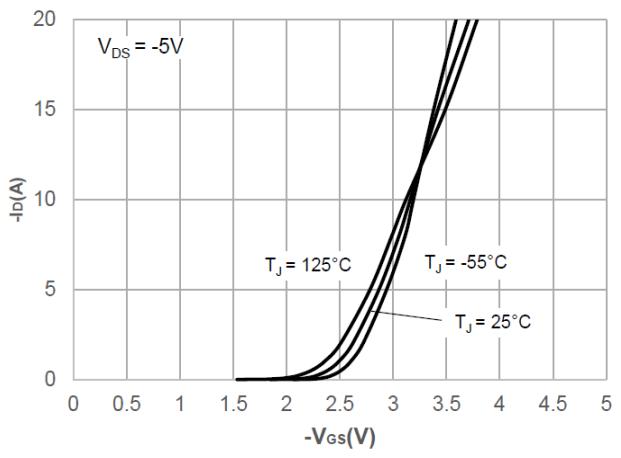


Figure 3: $R_{DS(ON)}$ vs. Drain Current

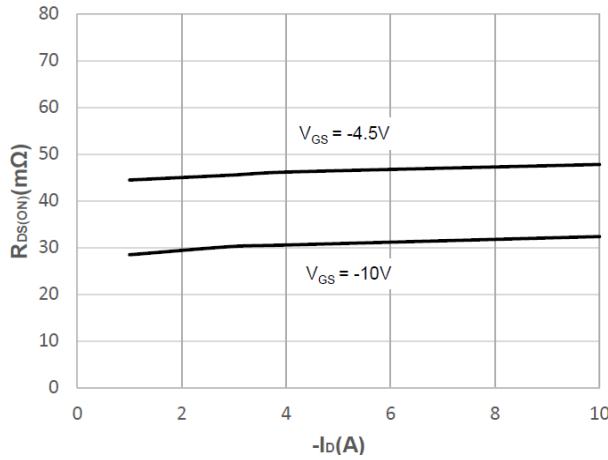


Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

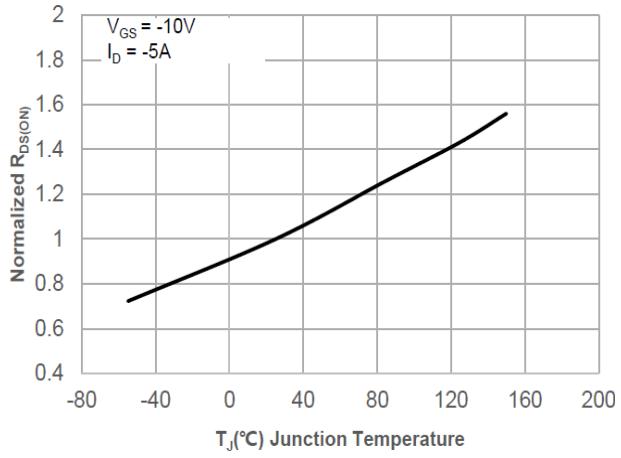


Figure 5: $BVDSS$ vs. Junction Temperature

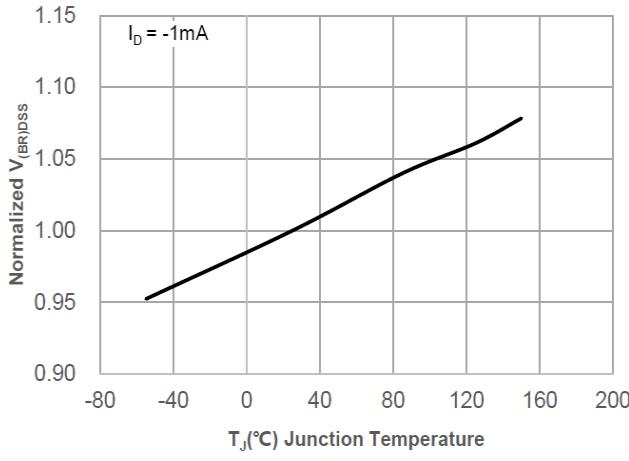
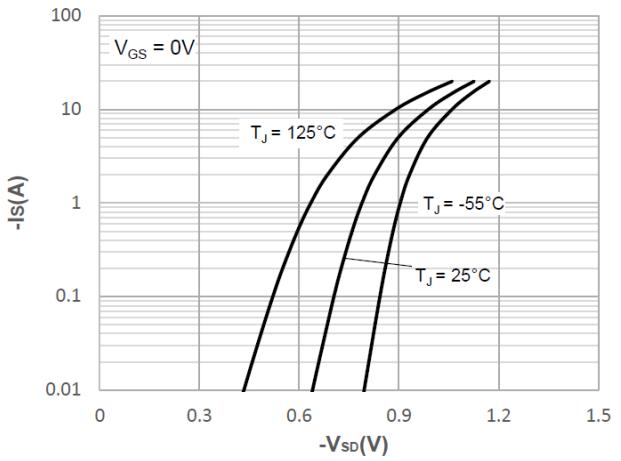
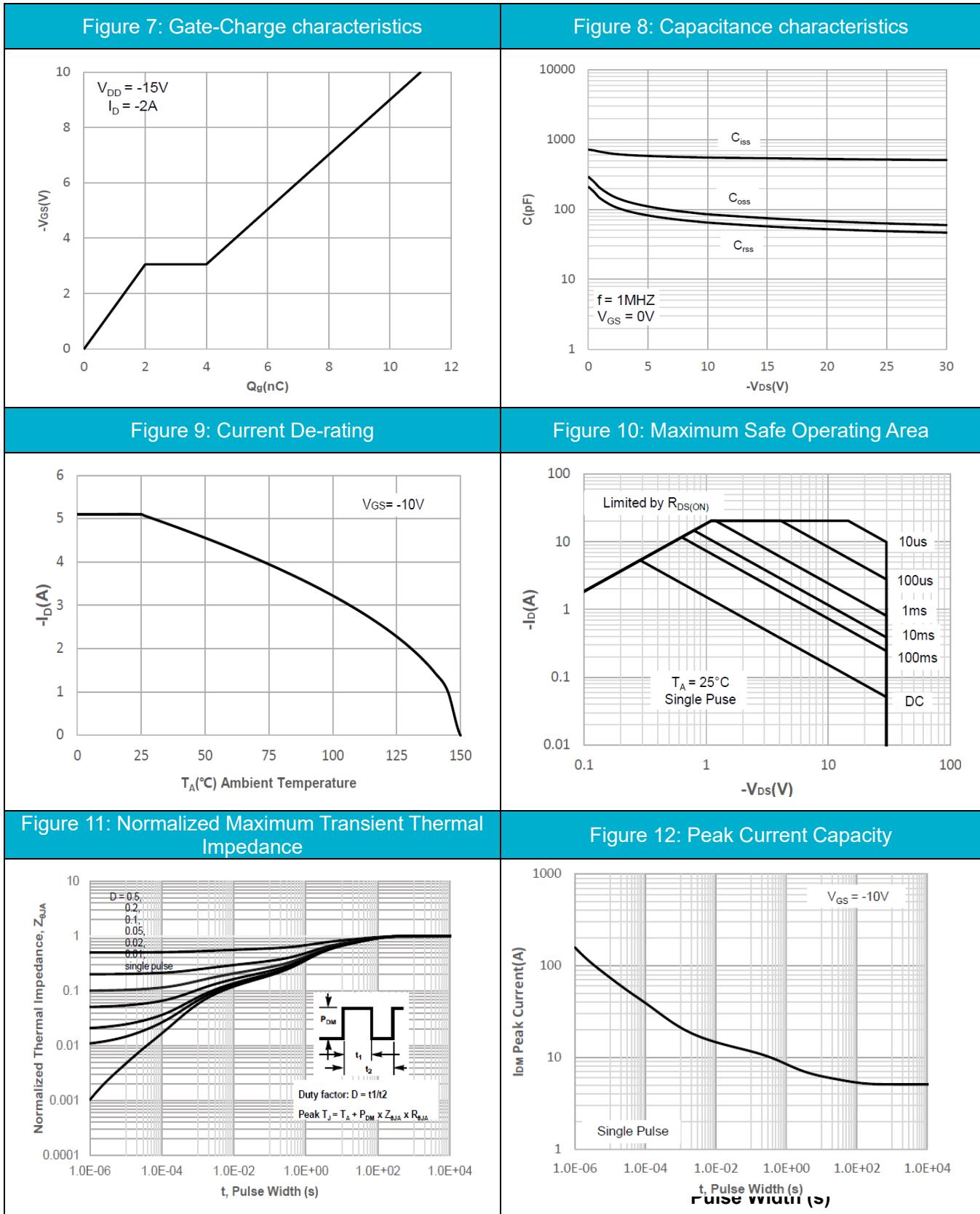


Figure 6: Body-Diode Characteristics



Typical Electrical and Thermal Characteristics



Test Circuit

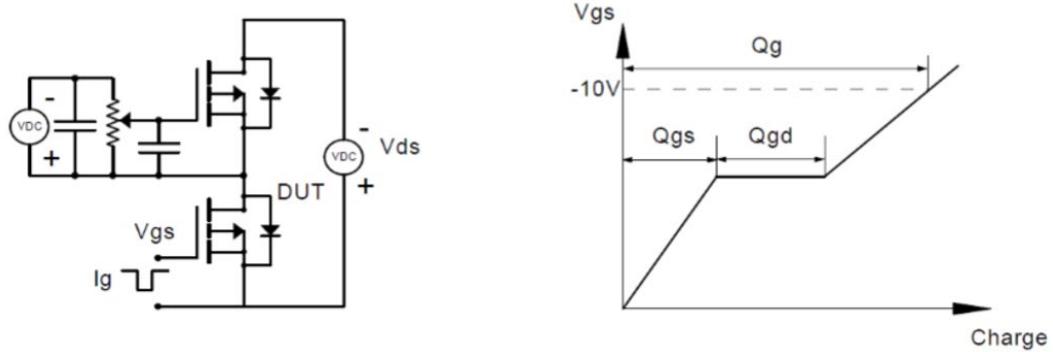


Figure1: Gate Charge Test Circuit & Waveforms

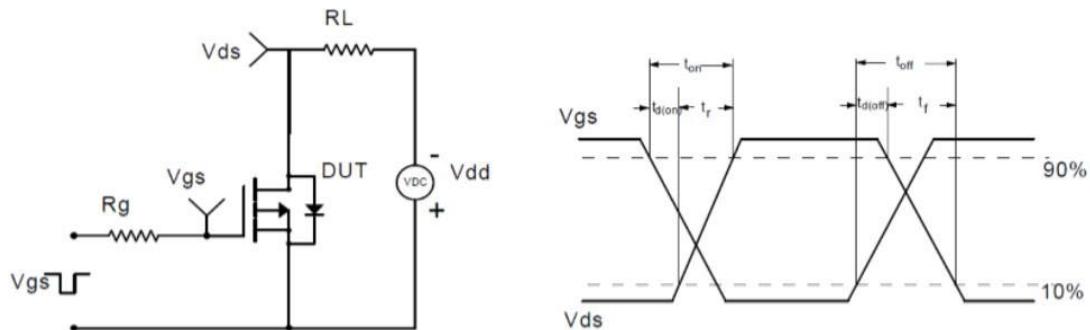


Figure2: Resistive Switching Test Circuit & Waveforms

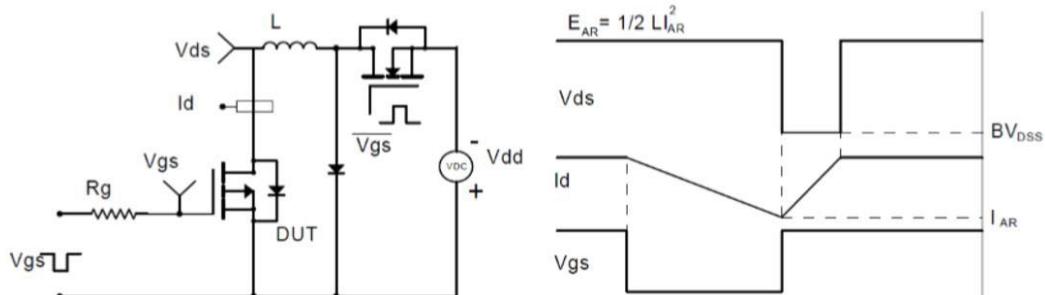


Figure3: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

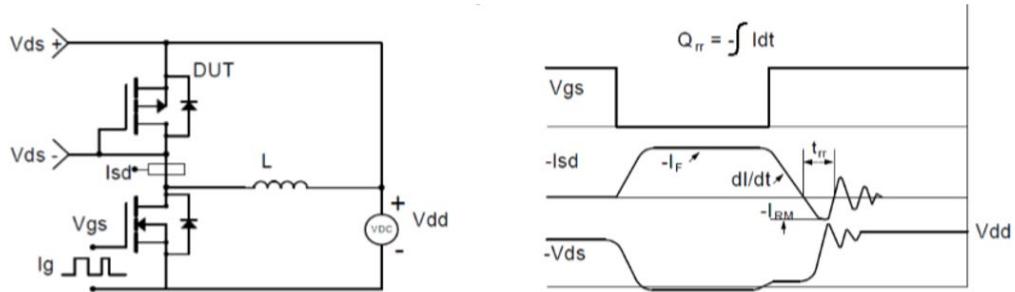


Figure4: Diode Recovery Test Circuit & Waveforms

SOP-8 Package Information

